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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/729,180	12/05/2003	Setho Sing Fee	2269-4738.2US (00-1113.02)	8592
24247	7590	08/17/2005	EXAMINER	
TRASK BRITT P.O. BOX 2550 SALT LAKE CITY, UT 84110			LE, THONG QUOC	
			ART UNIT	PAPER NUMBER
			2827	

DATE MAILED: 08/17/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

88

Office Action Summary	Application No. 10/729,180	Applicant(s) FEE ET AL.	
	Examiner Thong Q. Le	Art Unit 2827	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☐ Responsive to communication(s) filed on ____.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-20 is/are pending in the application.
4a) Of the above claim(s) ____ is/are withdrawn from consideration.
- 5) ☒ Claim(s) 1-6 and 11-20 is/are allowed.
- 6) ☒ Claim(s) 7-10 is/are rejected.
- 7) ☐ Claim(s) ____ is/are objected to.
- 8) ☐ Claim(s) ____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on ____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. ____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|--|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. ____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date ____ | 6) <input type="checkbox"/> Other: ____ |

DETAILED ACTION

1. Claims 1-20 are presented for examination.
2. Examiner's request for reconsideration of the allowance of the last Office action is persuasive and, therefore, the allowance of that action is withdrawn.

Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

4. Claims 7-10 are rejected under 35 U.S.C. 102(e) as being anticipated by Casper (U.S. Patent No. 6,184,067).

Regarding claims 7-10, Casper discloses a semiconductor die (ABSTRACT) assembly, comprising a semiconductor die having a plurality of bond pads (ABSTRACT, Figure 3, 34); a lead frame (Figure 4, 46) having a plurality of conductive leads, each conductive lead being electrically coupled at spaced locations on the conductive lead to

Art Unit: 2827

at least two bond pads of the plurality of bond pads (Column 2, lines 9-18, lines 28-31, "a plurality of bond pads are connected to **each one** of the plurality of conductive leads. Figure 4, conductive lead 46 couples more than one of pond pads 48).

Regarding claims 8-10, Casper discloses a dielectric encapsulant formed about the semiconductor die and partially about the lead frame (Column 1, lines 17-30), and a wire bond coupling each conductive lead at the spaced locations thereon to one of the at least two bond pads of the plurality of bond pads (Figure 4, 49, Figure 5, 49, Column 1, lines 30-35), and wherein each conductive lead includes a severance region configured to facilitate separation thereof into at least two mutually electrically isolate conductive elements (Figures 3-5, Column 1, lines 25-30).

5. Claims 7-10 are rejected under 35 U.S.C. 102(e) as being anticipated by Casper (U.S. Patent No. 6,587,892).

Regarding claims 7-10, Casper discloses a semiconductor die (ABSTRACT) assembly, comprising a semiconductor die having a plurality of bond pads (ABSTRACT, Figure 3, 34); a lead frame (Figure 4, 46) having a plurality of conductive leads, each conductive lead being electrically coupled at spaced locations on the conductive lead to at least two bond pads of the plurality of bond pads (Column 2, lines 9-18, lines 28-31, "a plurality of bond pads are connected to **each one** of the plurality of conductive leads. Figure 4, conductive lead 46 couples more than one of pond pads 48).

Regarding claims 8-10, Casper discloses a dielectric encapsulant formed about the semiconductor die and partially about the lead frame (Column 1, lines 17-30), and a wire bond coupling each conductive lead at the spaced locations thereon to one of the

Art Unit: 2827

at least two bond pads of the plurality of bond pads (Figure 4, 49, Figure 5,49, Column 1, lines 30-35), and wherein each conductive lead includes a severance region configured to facilitate separation thereof into at least two mutually electrically isolate conductive elements (Figures 3-5, Column 1, lines 25-30).

Allowable Subject Matter

6. Claims 1-6, 11-20 are allowed.

Claims 1-13 include allowable subject matter since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations. Casper (U.S. Patent No. 6,184,067), Casper (U.S. Patent No. 6,587,892, and others, does not teach the claimed invention having a recess in the dielectric encapsulant between at least one conductive element of the at least a first set of conductive elements and at least one adjacent conductive element of the at least one other set of conductive elements.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thong Q. Le whose telephone number is 571-272-1783. The examiner can normally be reached on 8:00am-5:00pm M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Hoai V. Ho can be reached on 571-272-1777. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Thong Q. Le
Primary Examiner
Art Unit 2827

THONG LEI
PRIMARY EXAMINER